New Product Introduction October 2026

MICROCONTROLLER

AURIX™ TC48x automotive microcontroller for zone ADAS and chassis applications

PSOC™ Control C1 Arm® Cortex®-M0 cost-effective motor control with real-time performance

POWER

CoolSET™ System in Package (SiP)

SPOC™ Wire Guard 12V Automotive eFuse with SPI

SECURITY AND SMART CARD SOLUTIONS

My-d™ move NFC for high-volume applications

SENSOR TECHNOLOGY

XENSIV™ TLE55493iC(D) wheel speed sensor

XENSIV™ TLI5572 cost-optimized miniature TMR current sensor, 5 V/3.3 V for battery powered tools, robots and drones

XENSIV™ TLx49012 digital Hall-based angle sensor family for automotive, robotics and industrial applications

XENSIV™ TLE5571 TMR-based magnetic current sensor

Classification: Restricted document! The information presented is valid from October 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

EVALUATION BOARDS

Evaluation Board for EiceDRIVER™ 2EDL6014AC-G2D in a buck converter topology using OptiMOS™

Evaluation board for EiceDRIVER™ 2EDL900G3 in a buck converter topology using OptiMOS™

PSOC™ Edge E84 HMI Kit for rapid prototyping and evaluation of next-generation Edge AI applications

DEMO_HV_PACKAGE innovative top-side cooled package solution for high-voltage applications

XENSIV™ BGT60CUTR13AIP CMOS 60 GHz radar SMD module

PLATFORMS

DRIVECORE™ TC4 IT2 pre-integrated software bundle for automated driving, ADAS, and robotics applications

AURIX™ TC48x automotive microcontroller for zone ADAS and chassis applications

Accelerate your architecture with AURIX™ TC48x MCUs, advanced members of the TC4x family. Built on 28 nm automotive-grade technology, they deliver deterministic multicore performance and high-speed connectivity for zonal controllers, integration platforms and safety-critical systems—supported by proven quality, robust tools and global application expertise.

Features

- 4/4 lockstep cores
- 400 MHz core frequency
- Up to 16 MB RRAM +0.5 MB CSRM NVM
- 3.3 MB SRAM
- 20+2 CAN FD + CAN XL interfaces
- 3x 10/100 Mb Ethernet modules
- 1x 2.5 Gbps Ethernet module
- Up to 73 analog input pins

Benefits

- Large local memories for fast access to more data
- HW routing engines and bridges
- CSRM: high-performance security module with private CPU, memories and crypto accelerators
- CSS: distributed crypto and hash engines for secure CAN/Ethernet communication
- Software backwards compatible with the AURIX™ TC3x MCUs

Competitive advantage

- Scalable platform architecture enabling platform reuse across vehicle domains
- Higher integration reducing ECU count and overall system cost
- Deterministic real-time performance for mission-critical applications
- Advanced safety architecture supporting ASIL-D compliance
- Integrated cybersecurity protecting vehicle data and IP
- High-bandwidth connectivity for zonal and software-defined architectures

Target applications

- ADAS and autonomous driving
- Automotive gateway
- Chassis control and safety
- In-vehicle infotainment and HMI

Product collaterals/online support

Product page

Product overview incl. datasheet link

OPN	SP Number	Package
TC489QP16NF400MCAAKXUMA1	SP005874838	PG-LFBGA-436
TC487QP16NF400MSAAKXUMA1	SP005874228	PG-LFBGA-292
TC487QP16NF400MCAAKXUMA1	SP005874836	PG-LFBGA-292
TC487QP12NF400MCAAKXUMA1	SP006107824	PG-LFBGA-292

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PSOC™ Control C1 Arm® Cortex®-M0 cost-effective motor control with real-time performance

The PSOC™ Control C1 family of MCUs, based on Arm® Cortex®-M0, delivers cost-effective motor control for consumer and industrial markets. Featuring field-oriented control (FOC), this family accelerates time-to-market via the ModusToolbox™ Motor Suite. Target applications are home appliances, HVAC systems, power tools, and light EV chargers, the PSOC™ Control C1 family enables rapid deployment of advanced motor-driven solutions.

Features

- Core frequency: 48 MHz, Peripherals clock: 96 MHz
- Flash 64 - 200 kB, 16 KB RAM
- Supply voltage range: 1.8 - 5.5 V
- Up to 14-ch. 12-bit ADC, 2x parallel S&H
- Up to 4x comparators
- 8x 16-bit motor control timers, 8x 16-bit general purpose timers
- 2x CAN interfaces
- 4x Serial Interfaces (SPI/UART/IIC/IIS)
- Temp range: -40°C to 105°C

Benefits

- Excellent real-time performance including MATH co-processor
- Fast and highly flexible PWM channels
- Programmable hardware interconnections between peripherals including logical combinations
- Programmable analog blocks

Competitive advantage

- Excellent price-performance ratio for single motor control
- Getting started easily by ModusToolbox™ Motor Suite
- Highly efficient field-oriented control (FOC)
- Flexible motor and algorithm support
- 15 year via Infineon's longevity program

Target applications

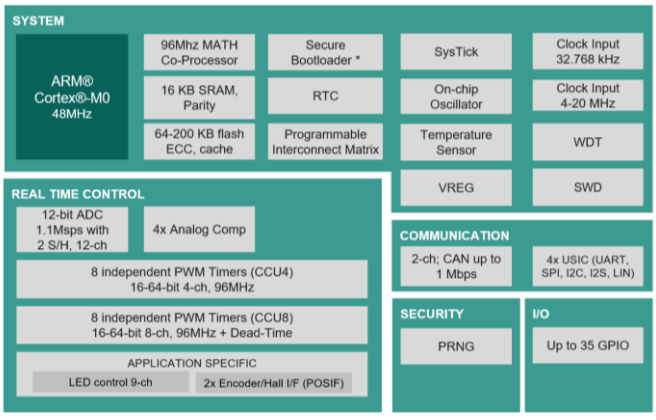
- Home and Professional Appliances
- Professional Tools
- Transportation
- General Purpose
- Lighting

Product collaterals/online support

Product page: PSOC™ Control C1 Arm® Cortex®-M0

Board page: KITPSC1M3EVKTOBO1

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
PSC1M2FBTBQ0ATXUMA1	SP006275449	PG-TSSOP-38
PSC1M2FBLEQ0ATXTMA1	SP006275458	PG-VQFN-40
PSC1M3FBLGQ0ATXTMA1	SP006275514	PG-VQFN-48
PSC1M3FBABQ0ATXUMA1	SP006275527	PG-LQFP-48
KITPSC1M3EVKTOBO1	SP006286575	LG-MADK-1

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CoolSET™ System in Package (SiP)

CoolSET™ SiP integrates a HV switch - CoolMOS™ P7 or CoolSiC™ - with a ZVS primary controller and secondary SR controller with CT link for reinforced isolated communication in a single SMD package for up to 150 W power delivery. The ZVS flyback solution cuts switching losses, improves EMI performance, and reduces BOM, while achieving efficiency above 94%.

Features

- Integrated 800 V CoolSiC™ or 800 V/950 V avalanche-rugged CoolMOS™ P7
- 950 V startup cell
- Novel ZVS with QR flyback operation
- Integrated synchronous rectification
- Built-in primary and secondary control
- Reinforced isolated communication

Benefits

- 94% efficiency
- < 30 mW standby consumption
- Up to 150 W output in SMD
- Industrial applications qualified

Competitive advantage

- Highest integration with primary, secondary, power switch, and reinforced isolation in one package
- > 94% efficiency with low EMI thanks to ZVS flyback operation
- Smaller footprint and lower BOM for cost-effective designs
- Industrial-grade reliability with reinforced isolation and robust protection
- Fast time-to-market through a fully integrated solution qualified against stringent EU regulatory requirements

Target applications

- Server power supply units (PSU)
- Refrigerators and freezers
- Washing and drying
- Induction cooking
- Heating ventilation and air conditioning (HVAC)
- Power conversion

Product collaterals/online support

Product family page

Product overview incl. datasheet link

OPN	SP Number	Package
ICE180LMXUMA1	SP006273828	PG-DSO-27
ICE183ZCMV001XUMA1	SP006172823	PG-DSO-27
ICE184EMV001XUMA1	SP006172803	PG-DSO-27
ICE184LMV001XUMA1	SP006172799	PG-DSO-27
ICE184ZCMV001XUMA1	SP006172831	PG-DSO-27
ICE186EMV001XUMA1	SP006172807	PG-DSO-27
ICE186LMV001XUMA1	SP006172839	PG-DSO-27
ICE186LMV101XUMA1	SP006138229	PG-DSO-27
ICE186XMV001XUMA1	SP006172843	PG-DSO-27
ICE186ZCMV001XUMA1	SP006172847	PG-DSO-27
ICE188LMXUMA1	SP006273820	PG-DSO-27

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SPOC™ Wire Guard 12V Automotive eFuse with SPI

SPOC™ Wire Guard BTS80009-SWPx-1ES, a highly integrated 12 V eFuse combining industry-leading low on-state resistance with software-configurable I2t wire protection via SPI up to 34.5 A. It offers fast, reliable protection and easy fuse-replacement to optimize wire harness design in modern power distribution systems. It supports all system architectures and functional safety compliance up to ASIL-D. Four feature sets are provided in this family and further 3 $R_{DS(on)}$ variants are also in the pipeline.

Features

- Single channel with $R_{DS(on)}$ of 1.1 mΩ (typical)
- Configuration via daisy chain capable SPI
- Integrated configurable I²t wire protection
- Automatic low current idle mode
- External commanded fast switch off
- Non-volatile memory
- SPI configurable undervoltage lockout
- ISO 26262-compliant development

Benefits

- Precise wire protection enables wire harness optimization and system protection
- Automatic idle mode to support minimum current consumption during parking
- Digital diagnosis with pre-warning and fast failure isolation
- Embedded capacitive load switching mode enables big capacitive loads charging
- Supports functional safety application with ISO 26262 compliant development

Competitive advantage

- Precise integrated wire protection via emulated I²t curve
- Non-volatile memory for software configurable load dependent fail-safe configuration and enhanced limp-home support
- Configurable power supply protection by commanded fast off and configurable undervoltage lockout for power net stability
- ISO 26262 Safety Element out of Context for safety requirements up to ASIL-D
- Less PCB space compared gate driver ICs plus MOSFET solution for this current range

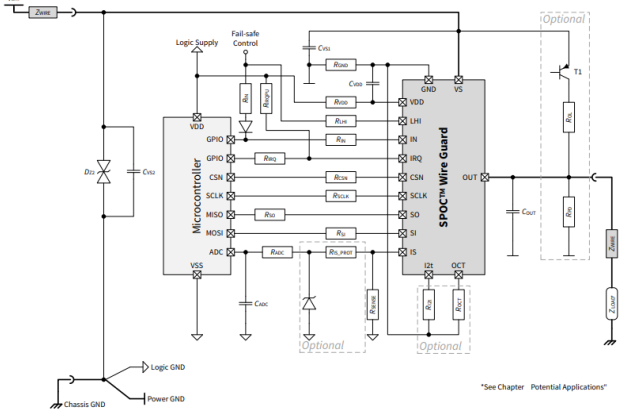
Target applications

- Wire harness protection
- Battery management system
- Automotive power distribution unit
- Zone control unit
- Fuse and relay replacement
- Software-defined vehicles

Product collaterals/online support

Product family page

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
BTS80009SWPF1ESXUMA1	SP006094813	PG-TSDSO-24

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My-d™ move NFC for high-volume applications

My-d™ move NFC is a cost-effective NFC Type 2 Tag built for high-volume applications needing reliable, secure tap interactions without complexity. Compatible with NFC smartphones worldwide, it offers password protection, unique IDs and block locking for cost-effective security. Pre-initialized with an empty NDEF message, it speeds deployment and reduces programming time. My-d™ move delivers reliable, sustainable and affordable NFC experiences at scale.

Features

- Contactless interface compliant with ISO/IEC 14443 type A
- 7-byte unique ID
- NFC Forum Type 2 Tag certified
- 152 bytes of memory
- Memory protected by 32-bit password using configurable retry counter
- NFC initialization at delivery, ready for use
- 16-bit customizable value counter

Benefits

- Universal interoperability with NFC-enabled smartphones and readers for seamless tap-to-access experiences requiring no external power
- Password protected read/write access to user data with retry counter to limit attempts to access data
- Enhance engagement by accessing URLs or exchanging data with or without apps, ideal for consumer and logistics use cases.
- NFC initialization on delivery – ready to be personalized
- Cost effectiveness paired with small footprint for mass production with existing machines

Competitive advantage

- Cost effective solution for high volume applications
- Support for open standards
- NFC Forum Type 2 Tag certified
- Long term trustworthy sourcing
- Memory protected by 32-bit password using configurable retry counter
- NFC initialization at delivery, ready for use
- 7-byte unique ID
- Temperature ranges from -25˚C to +70˚C
- Offered in bare die and TSNP package options

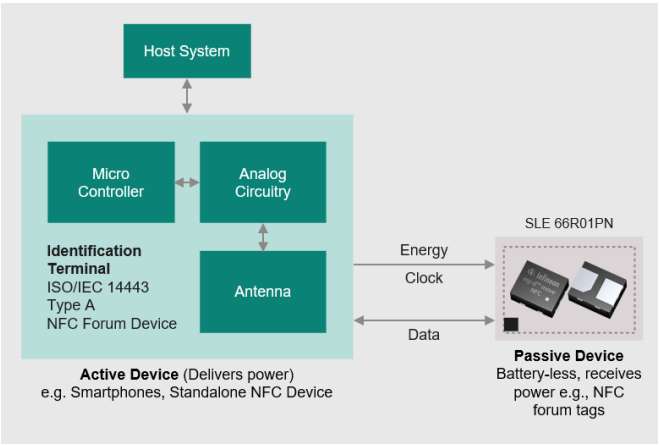
Target applications

- Consumer Engagement
- Smart cards and marketing
- Accessory identification and configuration
- Electronic Shelf Labels (ESL)
- Data storage and tracing

Product collaterals/online support

Product page

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
SLE66R01PNNBX1SA6	SP006035948	--
SLE66R01PNTSNP2XTMA1	SP005865524	PG-TSNP-2

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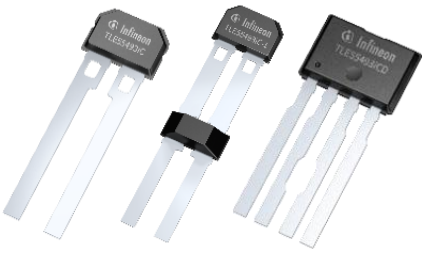
XENSIV™ TLE55493iC(D) wheel speed sensor

Infineon's TLE55493iC wheel speed sensor uses TMR technology for automotive applications such as ABS, ESC and ADAS. It delivers high sensitivity, fast and accurate speed detection, immediate valid direction from the first pulse and high-resolution protocols for parking and driving systems. The TLE55493iCD version integrates two dies in one package for redundant brake systems.



Features

- Low jitter (iTPMS)
- High airgap
- Real flexible read
- Compliant according to ISO 26262 ASIL-D process
- Fast direction detection
- High resolution protocols
- Dual die sensor option for redundancy

Benefits

- Immediate valid direction with 1st pulse
- High protocol variants enable accurate, faster and smoother control of the car movement
- Same TMR chip will be re-used in galvanic isolated dual die package
- Improved duty cycle

Competitive advantage

- High resolution for automated parking
- Immediate direction detection
- Improved duty cycle stability
- Improved stray field robustness
- Vibration robustness

Target applications

- Automotive braking solutions

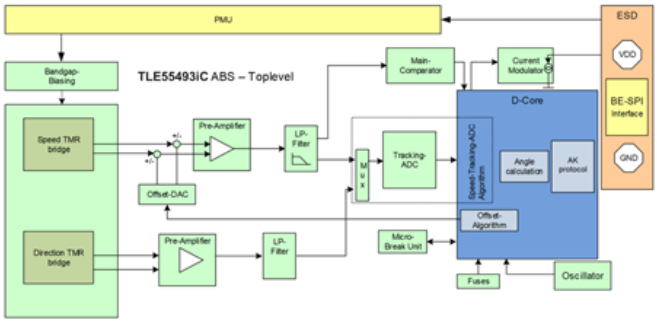
Product collaterals/online support

Product page: TLE55493ICLRXTMA1

Product page: TLE55493ICLR4HXTMA1

Product page: TLE55493ICDLRXTMA1

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLE55493ICLRXTMA1	SP005904492	PG-SSO-2
TLE55493ICLR4HXTMA1	SP005904498	PG-SSO-2
TLE55493ICDLRXTMA1	SP005972683	PG-SSO-4

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XENSIV™ TLI5572 cost-optimized miniature TMR current sensor, 5 V/3.3 V for battery powered tools, robots and drones

XENSIV™ TLI5572 is a Tunnel Magneto Resistance (TMR) coreless current sensor, ideal for cost-sensitive current sensing applications. It provides an amplified high-speed analog output signal replacing shunts and their respective isolated or non-isolated operational amplifiers. The sensor's external current rail design allows measurement of currents above 1 kA with high resolution and precision, ensured by minimal noise on the analog output. The TLI5572 family supports 3.3 V and 5 V supply voltage and consists of six different pre-calibrated sensitivity ranges (TLE version will be available later).

Features

- Fully isolated measurement of current up to >1 kA
- 3.3 V and 5 V supply voltage
- > 1 MHz bandwidth
- Ultra-low noise analog output
- Operating range -40°C to 150°C
- Magnetic measurement ranges from ±4 mT to ±35 mT
- Product qualification according to JEDEC JESD47

Benefits

- Cost-efficient TMR current sensor as shunt replacement
- Small design footprint and minimal PCB area consumption
- System level space and cost savings
- Isolated current measurement
- High ampacity of +/-1000 A
- Highly robust system design
- Great fit for SiC and GaN-based high power density applications
- Ideal in extreme operating conditions

Competitive advantage

- Ultra-low noise, up to 8.1 µTRMS until 1 MHz bandwidth
- Sensitivity error over temperature and lifetime (max. ±2.7%)
- Pre-calibrated offset and sensitivity over temperature secures good accuracy and reduces system temperature compensation

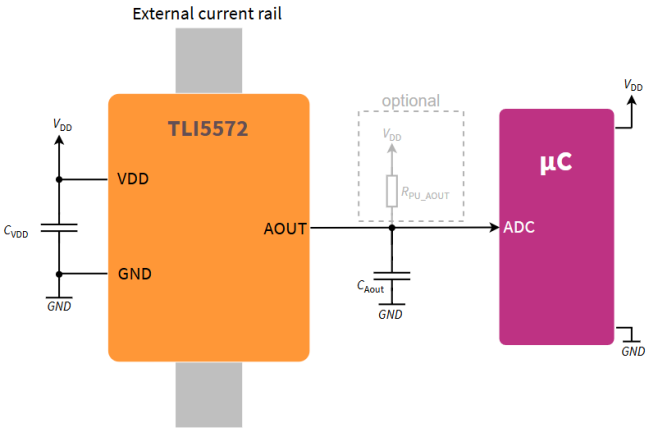
Target applications

- Battery powered tools
- Service robots and drones
- e-Bikes and e-Scooters
- Home appliances and smart home
- Flaps, actuators, power-closing and pumps
- Redundant sensing

Product collaterals/online support

Product family page

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLI5572AE04E1E0001XTSA1	SP006042435	PG-SOT23-6
TLI5572AE06E1E0001XTSA1	SP006042443	PG-SOT23-6
TLI5572AE08E1E0001XTSA1	SP006042450	PG-SOT23-6
TLI5572AE12E1E0001XTSA1	SP006042470	PG-SOT23-6
TLI5572AE15E1E0001XTSA1	SP006042493	PG-SOT23-6
TLI5572AE24E1E0001XTSA1	SP006034925	PG-SOT23-6

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XENSIV™ TLx49012 digital Hall-based angle sensor family for automotive, robotics and industrial applications

The XENSIV™TLx49012 is Infineon's next-generation digital angle sensor family, part of the magnetic position sensors portfolio, designed for automotive (TLE49012) and industrial (TLI49012) motor control applications. Built on proven Vertical Hall technology, the TL x49012 sensor delivers high-accuracy angle measurement with exceptional cost-to-performance ratio.

Features

- Unique system self-calibration feature
- Multiple interface options: SPI, ABZ, PWM, UVW
- Extremely low latency of 1.5 µs
- End of shaft as well as off-axis/out-of-shaft capability
- High accuracy: angle error of 0.1°
- Magnetic field range 20-120 mT
- Small form factor in VSON-8-2 package

Benefits

- On-chip system self-calibration providing easy and of line calibration and highest angle accuracy over lifetime
- Design flexibility with freedom to position the sensor as you like
- High-speed signal processing, suitable for very fast applications
- Excellent cost-to-performance ratio
- Easy integration with pre-calibrated and pre-programmed sensitivity
- TLE49012 with ASIL B functional safety compliance acc. to ISO26262, AEC-Q100 Grade 0

Competitive advantage

- Integrated system self-calibration for end of shaft and out of shaft measurements
- Angle error of just 0.1° across a magnetic field of 30 to 120 mT
- Programmable and flexible design with 4 different interface options

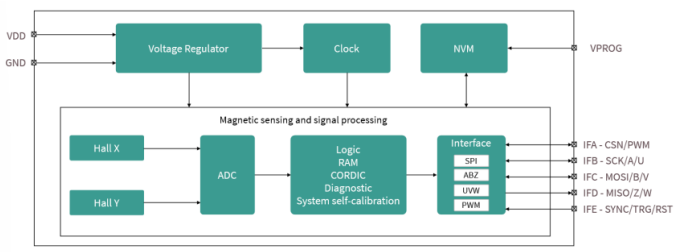
Target applications

- TLE-version: Automotive pumps, Automotive valves/flaps/actuators, Window cleaning and transparency, Electric power steering (EPS),
- Suspension ride control, electromechanical brake (EMB), e-motorbikes/scooter and pedelecs
- TLI-version: Robotics (e.g.humanoids, dexterous hands), durable medical equipment (DME), electric forklift and industrial drives, PC and gaming accessories

Product collaterals/online support

Product family page

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLE49012E0001XTMA1	SP005858930	PG-VSON-8
TLE49012S0001XTMA1	SP005858906	PG-VSON-8
TLE49012S0002XTMA1	SP005858928	PG-VSON-8
TLI49012E0001XTMA1	SP006268934	PG-VSON-8

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XENSIV™ TLE5571 TMR-based magnetic current sensor

XENSIV ™ TLE5571 is a Tunnel Magneto-Resistance (TMR)-based coreless current sensor with an ultra-fast, single-ended analog output and overcurrent detection (OCD), suitable for protection and high-frequency switching applications that require current sensing with an extremely small input-to-output delay. The minimum bandwidth of 2.5 MHz makes it suitable for SiC and GaN-based applications.

Features

- Fully isolated measurement of currents up to >2 kA
- 5 V supply voltage
- Bandwidth > 2.5 MHz
- Ultra-low-noise analog output
- Operating temperature range -40°C to 150°C
- Magnetic measurement ranges from ±5 mT to ±30 mT
- Product qualification compliant with JEDEC JESD47 standards
- Ultra-fast over-current detection (<150 ns)
- Adjustable over-current detection threshold using an external voltage

Benefits

- Cost-efficient TMR-based current sensor for protection
- Small design footprint with minimal PCB area consumption
- System-level space and cost savings
- Isolated current measurement for enhanced safety
- High ampacity of ±2000 A
- Highly robust system design
- Ideal for SiC and GaN-based high-power density applications
- Optimized for extreme operating conditions

Competitive advantage

- Linear monolithic TMR technology
- Higher signal-to-noise ratio (SNR)
- Configurable OCD threshold
- Additional wire-on-chip (WOC) test capability for sensor diagnostic features

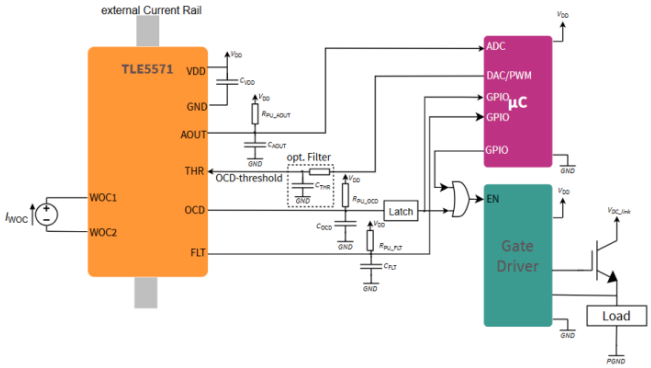
Target applications

- eFuse
- Circuit breakers
- Battery disconnect switch
- Motor drives

Product collaterals/online support

Product family page

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
TLE5571AE36O5IS0001XUMA1	SP005911576	PG-TDSO-16
TLE5571AE24O5IS0001XUMA1	SP005911580	PG-TDSO-16
TLE5571AE12O5IS0001XUMA1	SP005911584	PG-TDSO-16
TLE5571AE06O5IS0001XUMA1	SP005911631	PG-TDSO-16

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Evaluation Board for EiceDRIVER™ 2EDL6014AC-G2D in a buck converter topology using OptiMOS™

It is a general-purpose evaluation board for Infineon's EiceDRIVER™ 2EDL6014AC-G2D gate driver, together with the OptiMOS™ ISC016N08NM8SC and ISC031N08NM6SC 80 V MOSFETs.

This board includes an optimized layout for a hard-switching half-bridge configuration, as well as waveform measurement points and other useful features that enable easy lab bench characterization of the gate driver and the power switches.

Features

- Half-bridge open loop buck converter configuration using 2EDL6014AC-G2D to drive OptiMOS™ power switches
- Configurable in either of the two configuration: Non-voltage-level-shifted or Voltage-level-shifted
- Selectable OUTA driving source current via STA feature
- Wide gate drive voltage operating range
- Test points ready for waveform measurements

Benefits

- Optimized for efficient benchmarking
- Accelerates driver validation setup
- Supports fast prototyping
- Simplifies driver testing setup
- Optimized for flexibility

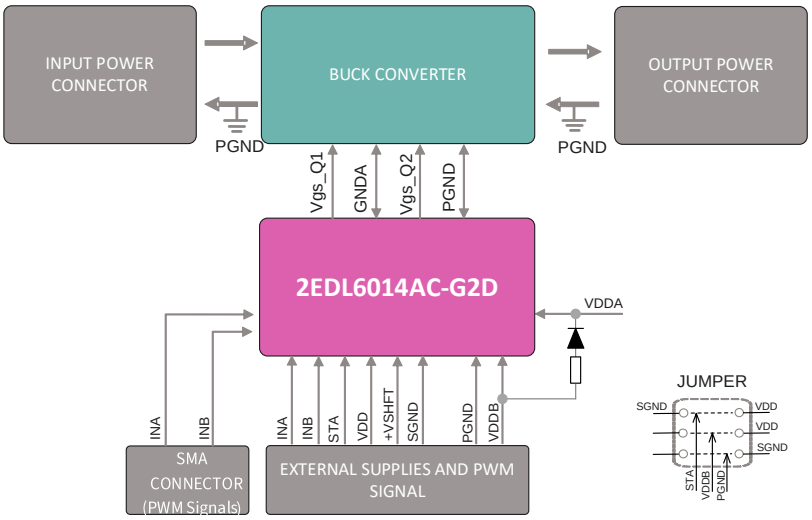
Product collaterals/online support

Board page

Target applications

- Intermediate Bus Converter (IBC)
- Non-isolated multi-level converters
- Switched-capacitor converters topologies (HSC, ZSC...)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
EVALHB2EDL6014ACTOBO1	SP006314237	LG-MADK-1

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Evaluation board for EiceDRIVER™ 2EDL900G3 in a buck converter topology using OptiMOS™

EVAL_HB_2EDL900G3_SI is a general-purpose evaluation board for Infineon's EiceDRIVER™ 2EDL900G3 gate driver, together with the OptiMOS™ ISC016N08NM8SC and ISC031N08NM6SC 80 V MOSFETs. This board includes an optimized layout for a hard-switching half-bridge configuration, as well as waveform measurement points and other useful features that enable easy lab bench characterization of the gate driver and the power switches.

Features

- Half-bridge open loop buck converter configuration using 2EDL900G3 to drive OptiMOS™ power switches
- Configurable in either of the two configurations: non-voltage-level-shifted or voltage-level-shifted
- Configurable MODE of operation, such as single PWM mode or LI/HI input mode
- IMON signal monitoring via DC resistance (DCR) current sensing of the output inductor
- Wide gate drive voltage operating range
- Test points ready for waveform measurements

Benefits

- Easier evaluation of features of 2EDL900G3
- Optimized for flexibility
- Supports fast prototyping
- Simplifies driver testing setup

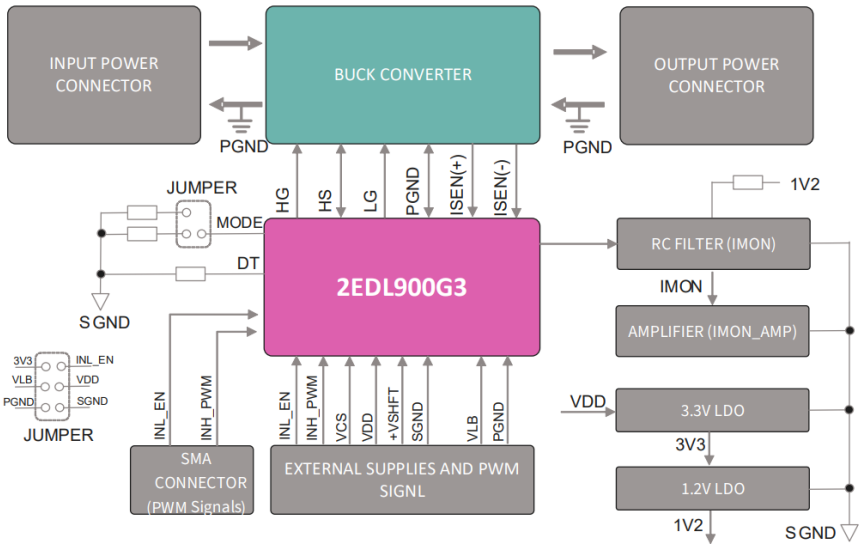
Product collaterals/online support

Board page

Target applications

- IBC AI server application
- 48 V/54 V down conversion for datacom and telecom
- 800 V/+/-400 V LLC converters (secondary side)
- Multiphase interleaved buck converters (ILVB)
- Hybrid switched capacitor converters (HSCC)

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
EVALHB2EDL900G3SITOBO1	SP006310980	LG-MADK-1

Classification: Restricted document! The information presented is valid from October 1st 2026. Please check the latest Distribution Price Book for current prices and minimum quantities.

PSOC™ Edge E84 HMI Kit for rapid prototyping and evaluation of next-generation Edge AI applications

The PSOC™ Edge E84 HMI kit is a hardware evaluation platform for rapid prototyping and evaluation of next-generation HMI for Edge AI applications based on the high-performance PSOC™ Edge E84 MCU. This kit provides a variety of sensors and interfaces to get started on HMI use cases and Edge AI designs, in an application-centric form factor.

This comprehensive HMI kit provides a 4-inch capacitive touch display, camera, microphones and speakers to evaluate HMI use cases within voice, vision and graphics capabilities as well as a CYW55513 Wi-Fi and BT module. This evaluation kit helps accelerate time-to-market by enabling ML/AI-powered HMI application designs, built on a robust ecosystem, comprehensive documentation, and full use of Infineon's ModusToolbox™ software and DEEPCRAFT™ AI Suite.

Features

- Cortex®-M55 CPU with Helium™ DSP
- Advanced ML with Arm® Ethos™-U55 NPU
- Low-Power Cortex®-M33
- NNLite for ultra-low power NPU
- Analog/digital voice/audio microphones
- 60GHz radar sensor for advanced sensing
- USB camera for AI/ML vision applications
- 4-inch, 480x480 screen with touch
- 6-axis accelerometer and gyroscope
- Humidity and temperature sensors
- 64MB Octal SPI HYPERRAM
- 128MB Octal SPI NOR Flash

Benefits

- Edge AI acceleration for next-gen apps
- Multiple data collecting sensors
- Application-centric form factor
- Rich integration to reduce BOM
- Mikro-E expansion slots
- Near and far-field local voice commands
- Radar touchless gestures and proximity sensing
- Interactive computer vision capabilities
- Full compendium of design files for design replication

Competitive advantage

- Application-centric form factor
- Self-contained for quickly developing HMI edge intelligence
- AI-powered experiences at the edge without cloud dependence
- Premium graphics on low-power embedded systems
- Intuitive voice, touch and gesture interactions
- Reduce design risk with production-ready hardware

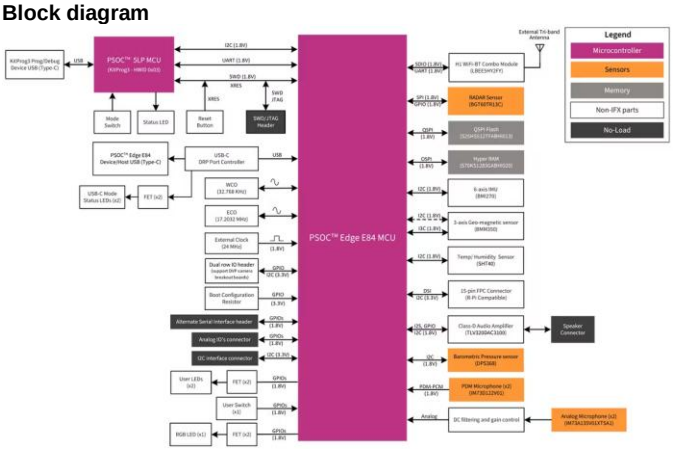
Target applications

- Smart thermostat
- Coffee machines and grinders
- Microwave ovens and ovens
- Washing and drying
- Domestic robots
- Residential alarm and security

Product collaterals/online support

Board page

Block diagram



Product overview incl. user guide link

OPN	SP Number	Package
KITPSE84HMITOBO1	SP006248344	LG-MADK-1

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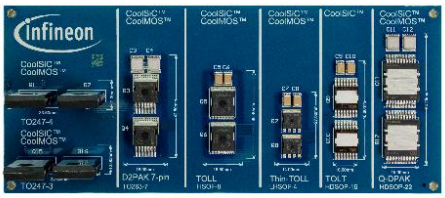
DEMO_HV_PACKAGE innovative top-side cooled package solution for high-voltage applications

Discover the benefits of Infineon's high-voltage power packages, featuring CoolSiC™ and CoolMOS™ technology. The Demo_HV_package board helps designers understand how to integrate our bottom and top-side cooled packages effectively into their designs. Benefit from simplified assembly and reduced design complexity to achieve optimal thermal performance for highest efficiency and power density at lower system cost.



Features

- Improved power loop design
- Innovative cooling concepts: BSC and TSC
- Optimized design of the half bridge
- Lower stray inductance
- Kelvin source pin
- 3D concept: cooling and power loop integration

Benefits

- Faster and cheaper in production assembly
- Higher switching capabilities
- Better control and reduced power losses
- Possibility of double side PCB assembly

Competitive advantage

- Enables significantly higher power density and superior thermal performance compared to conventional through-hole and bottom-side cooled solutions, while reducing assembly complexity and accelerating design-in

Target applications

- Uni-directional and bi-directional On-Board Chargers (OBC)
- HV-LV DC-DC converters for electric vehicles
- Solid-state circuit breaker
- HV battery disconnect switches
- HV e-fuses
- AC-DC power conversion for telecom infrastructure
- Server power supply units
- EV charging systems
- Motor drives / motor control
- Photovoltaic

Product collaterals/online support

Board page

Product overview incl. application note link

OPN	SP Number	Package
DEMOHVPACKAGETOBO1	SP006130308	LG-MADK-1

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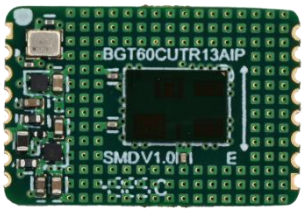
XENSIV™ BGT60CUTR13AIP CMOS 60 GHz radar SMD module

This SMD module features the XENSIV™ BGT60CUTR13AIP CMOS 60 GHz radar sensor. It is fully FCC and CE certified and allows customers to rapidly prototype using the PCB pad connectors. The fully modular certified surface-mounted device (SMD) reference design for the XENSIV™ BGT60CUTR13AIP CMOS 60 GHz radar sensor will also allow customers to copy and paste the PCB layout structure and enable a transfer of ID to ease FCC and CE certification efforts.



Features

- XENSIV™ BGT60CUTR13AIP radar sensor
- SMD module with PCB pad connectors
- FCC and CE certified module
- 17.7 x 12 mm² form factor
- Fast prototyping and reference design
- HW integration and design-in support
- 60 GHz radar sensing
- Ultra-low power for battery-powered IoT

Benefits

- Ideal for IoT, battery-powered devices
- Transfer of ID for FCC/CE certification
- Reduced certification efforts and costs
- Fast prototyping for CMOS radar
- Suited for customer field trials

Competitive advantage

- FCC and CE certified to ease product integration and certification
- Reduced costs by transfer of ID for certification
- Fast prototyping with ready to sell PCB design

Target applications

- Consumer electronics
- Heating ventilation and air conditioning (HVAC)
- Robotics
- Security camera and video doorbell
- Smart home and building

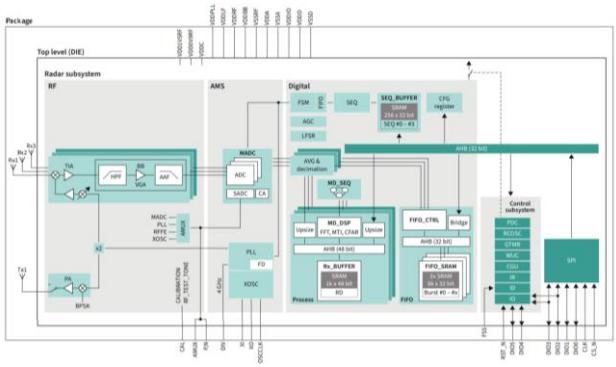
Product collaterals/online support

Board page

Product page

Block diagram

BGT60CUTR13AIP



Product overview incl. user guide link

OPN	SP Number	Package
SMDBGT60CUTR13AIPTOBO1	SP006268015	LG-MADK-1

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DRIVECORE™ TC4 IT2 pre-integrated software bundle for automated driving, ADAS, and robotics applications

DRIVECORE™ TC4 IT2 is a pre-integrated software bundle for automated driving, ADAS, and robotics applications. Built in collaboration with Intron / G-pulse around the Infineon AURIX™ TC4D9 safety MCU and high-performance SoCs, it combines Infineon's MCAL drivers, Vector's AUTOSAR software, and TASKING tools to accelerate development, improve functional safety (up to ASIL D) and reduce time-to-market.

Features

- Infineon's MCAL Driver: standardized interface to the AURIX™ microcontroller
- Vector's MICROSAR Classic: pre-integrated, real-time capable base software stack
- TASKING SmartCode: C/C++ Compiler Tool Chain for TriCore™ and PPU

Benefits

- Streamlined development: reduces development time and costs
- Improved reliability: ensures reliable functionality in safety-critical domains
- Increased productivity: provides a head start for developers

Competitive advantage

- Pre-integrated software stack
- All licenses included
- Quick start through included Demo and Getting Started Guide

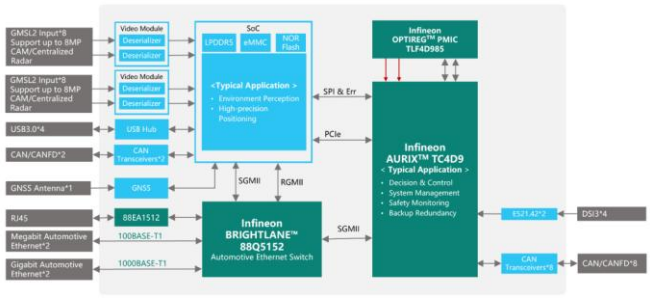
Target applications

- Automated driving
- ADAS
- Robotics applications

Product collaterals/online support

Product brief

Block diagram



Note: The BRIGHTLANE™ Ethernet Switch is available for certain models in the OPEN-ECU™ GDCU4xx series.

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